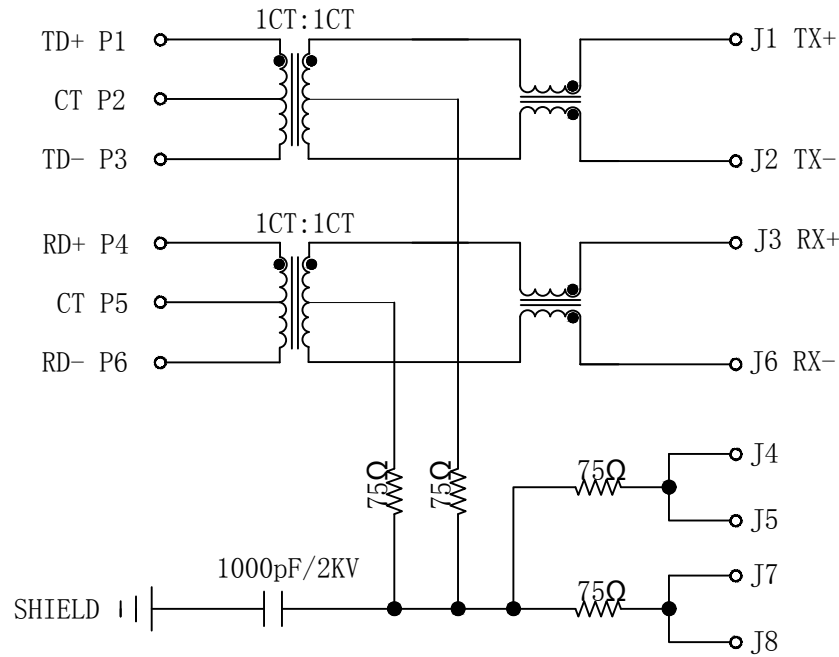


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/09	

PCB SIDE TO PHY

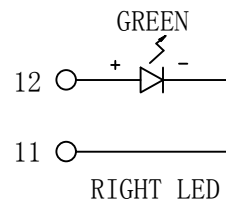
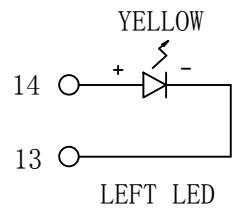


CABLE

Electrical Specification @25°C

- Turns Ratio($\pm 2\%$):
 (P1-P3) : (J1-J2) = 1:1
 (P4-P6) : (J3-J6) = 1:1
- Inductance: 350uH MIN
 @0.1V, 0.1MHz, 8mA DC Bias
- Insertion Loss:
 0.1MHz-100MHz: -1.2dB max
- Return Loss:
 1MHz-30MHz: -18dB min
 30MHz-80MHz: -12dB min
- Cross talk:
 1MHz-100MHz: -40dB
- Common to Mode Rejection
 30MHz-100MHz: -35dB
- Hipot: 1500Vrms
- Operating Temperature: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$.

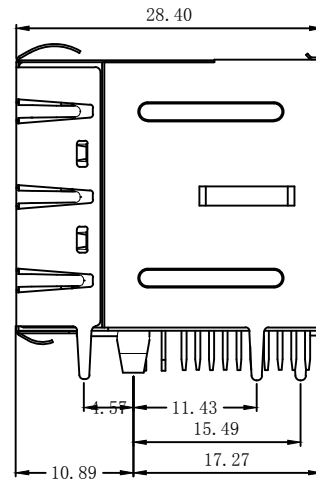
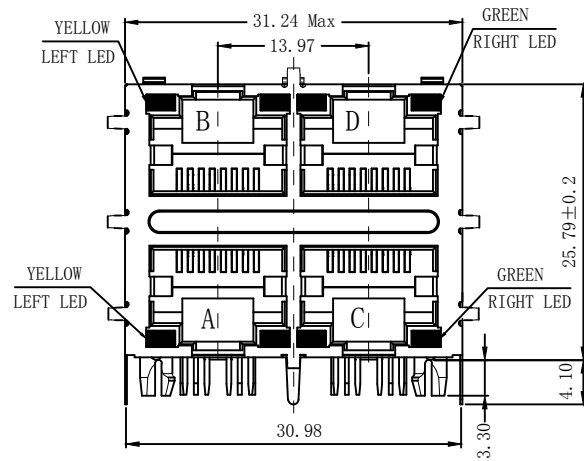
Emitting Color	λ_p (nm)	VF@IF=20mA	IR @VR=5V
GREEN	565	1.8~2.6V	10 μ A max
YELLOW	585	1.8~2.6V	10 μ A max



X:X	± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.25	CHKD:	TITLE: RJ45 . Transformer. 10/100 Base-T W/LED. 2x2 Ports.	
X:XXX	± 0.05	DR: TOM	PART NO. : LPJ27434-8AGNL	
ANGLES	$\pm 1^{\circ}$	UNIT: mm		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO. : LP11070926

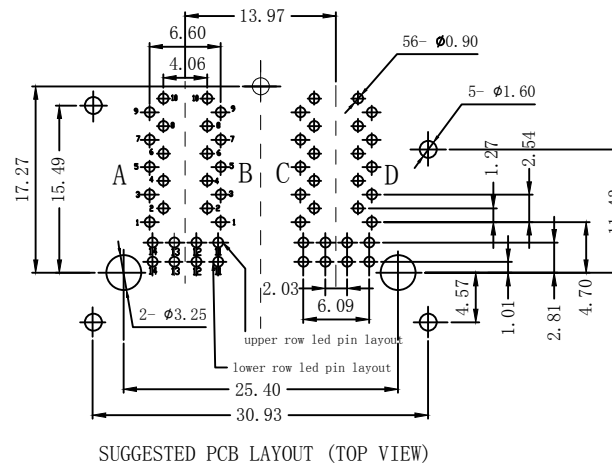
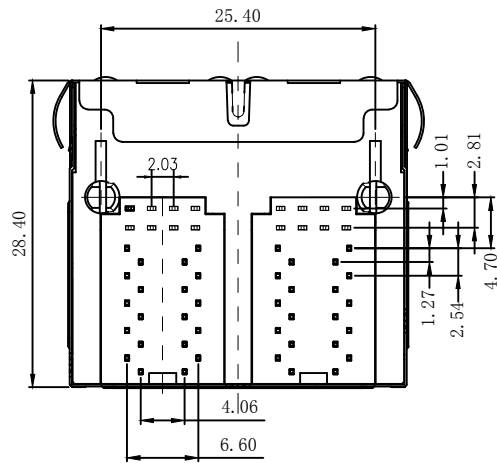
Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/07/09	



NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
 Housing: Thermoplastic UL94V-0
 Contact/Shield: Copper alloy
 Shield plating: Nickel
 Contact plating: Gold 30 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max, 5 Sec Max.



X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.25	CHKD:	TITLE: RJ45 .Transformer.10/100 Base-T W/LED.2×2 Ports.	
X:XXX	±0.05	DR: TOM	PART NO. : LPJ27434-8AGNL	
ANGLES	±1°	UNIT: mm		
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO. : LP11070926